

ABSTRACT OF THE DISCLOSURE

In the ceramic circuit board, within the through hole of the ceramic substrate is arranged the metal column which is 0 to $150\mu\text{m}$ shorter relative to the thickness of the ceramic substrate; the metal circuit plates are attached to both surfaces of the ceramic substrate to stop up the through hole; and the metal column and the metal circuit plate are bonded together via the brazing material. For its manufacture, the metal column with brazing material is used that is made 40 to $140\mu\text{m}$ longer relative to the thickness of the ceramic substrate by being formed of the metal column which is 0 to $150\mu\text{m}$ shorter relative to the thickness of the ceramic substrate and has its both ends coated with the brazing material.